# NON-SILICONE THERMAL PASTE

**series: ATPN**

- Eliminates air gaps between heat source and heat sink.
- Thermal conductivity of up to 4.5w/mk.
- Molecular structure prevents leakage and vaporization.
- Long term reliability.
- Good electrical insulation.
- Low rebound reduces load on electronic components.
- Compresses easily, absorbing dimensional tolerances.
- Typical applications include PCBs in automotive navigation systems, CIDs and ECUs, tablet devices, digital cameras, digital signage and manufacturing equipment.

## *NEW PRODUCT*

| Properties | ATPN-9613 | ATPN-4332 | ATP-9345 | ATP-1535 | Test Method |
|---|---|---|---|---|---|
| Thermal Conductivity (W/m-k) | 1.3 | 3.2 | 4.5 | 3.5 | ASTM D5470 |
| Viscosity (PaS) | 96 | 43 | 93 | 15000 (DIN 53018) | ISO 3219 |
| Temperature Range (°C) | -60 ~ 150 | -60 ~ 150 | -60 ~ 150 | -60 ~ 150 | - |
| Colour | White | Grey | Grey | Grey | - |
| Material | Non-silicone | Non-silicone | Non-silicone | Non-silicone | - |
| Density | 2.2 | 1.9 | 2.1 | 3.0 | ASTM D792 |
| Dielectric breakdown strength (V/mil) | 350 | - | - | 300 | ASTM D149 |
| Volume Resistivity (Ω-m_ | >10[11] | - | - | >10[13] | ASTM D257 |